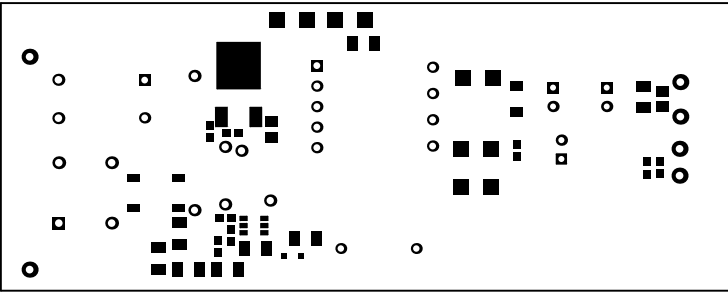
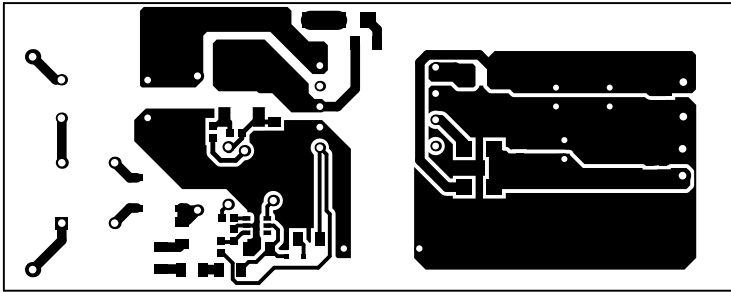


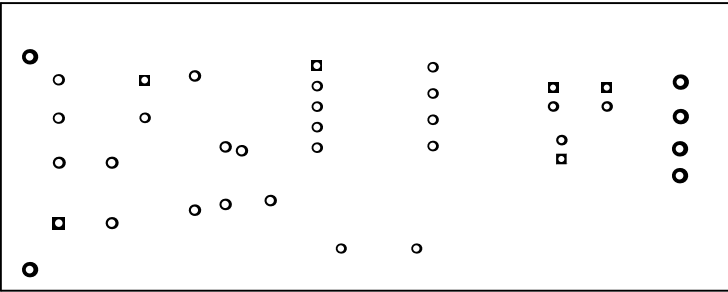
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 12/12/2016 5:51:28 AM	TEXAS INSTRUMENTS	



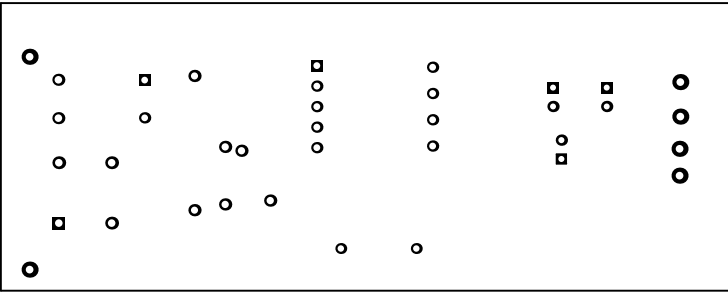
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 12/12/2016 5:51:29 AM		TEXAS INSTRUMENTS



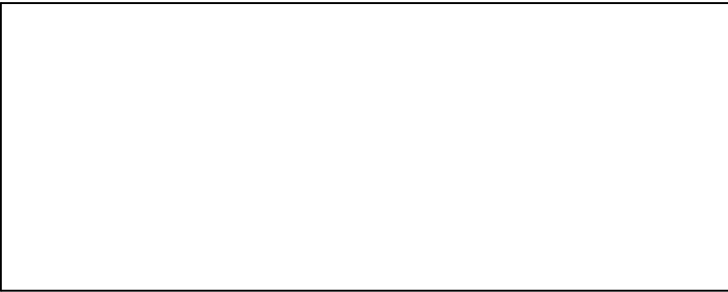
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 12/12/2016 5:51:31 AM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 12/12/2016 5:51:32 AM		TEXAS INSTRUMENTS

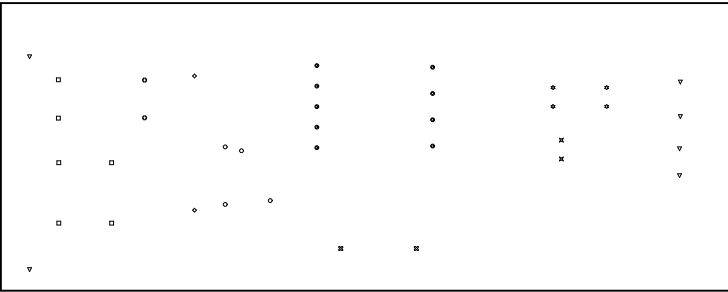


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/12/2016 5:51:33 AM		TEXAS INSTRUMENTS

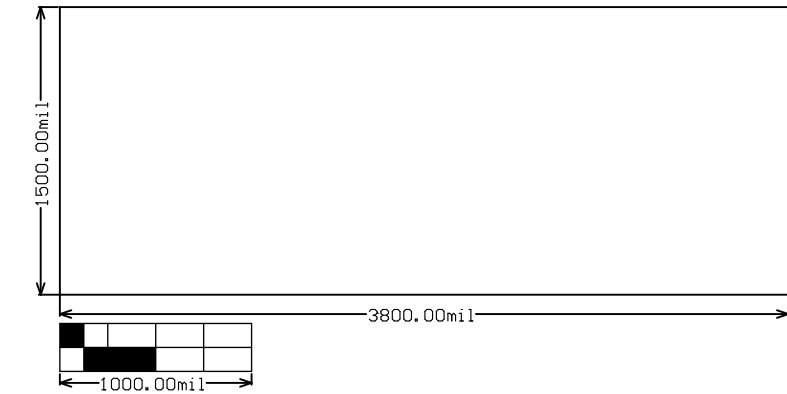


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 12/12/2016 5:51:35 AM		TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✳	4	31.00mil (0.787mm)	PTH	Round	Top Layer - Bottom Layer	
✂	2	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
✂	2	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⚙	2	35.00mil (0.889mm)	PTH	Round	Top Layer - Bottom Layer	
⦿	9	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
◇	2	37.00mil (0.940mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	38.00mil (0.965mm)	PTH	Round	Top Layer - Bottom Layer	
□	6	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
▽	6	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
	37 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 12/12/2016 5:51:36 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20339	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 12/12/2016 5:51:37 AM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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